Product name	Confidentiality level
E3276s	CONFIDENTIAL
Product version	Total 7 pages
V1.0	

E3276s HiLink Firmware Release Notes

V1.0

Prepared by	Peng Xiaolin	Date	2014-7-17
Reviewed by	Yu jianbing、He chunyong	Date	2013-7-17
Approved by		Date	

Huawei Technologies Co., Ltd.

Revision Record

Date	Revision version	FW-WebUI/HiLink Version	Change Description	Author
2013-9-10	*1.0*	*FW 22.436.09.00.00 WebUI 13.100.04.00.03*	*First version*	Peng xiaolin
2014-7-17	*1.0*	*FW 22.470.11.00.00 WebUI 17.100.03.00.03*	*Second version*	Peng xiaolin
2014-7-28	*1.0*	*FW 22.470.13.00.00 WebUI 17.100.03.01.03*	*Third version*	Peng xiaolin

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1　Main Features

The E3276s supports the following standards:

- LTE data service up to 130Mbit/s(Downlink) and 50Mbit/s(Uplink)
- DC-HSPA+ data service up to 43.2 Mbit/s
- HSPA+ data service up to 21.6 Mbit/s
- HSDPA packet data service of up to 14.4 Mbit/s
- HSUPA data service up to 5.76 Mbit/s
- WCDMA PS domain data service of up to 384 Kbit/s
- Equalizer and receive diversity
- microSD Card Slot (Up to 32G)
- Data and SMS Service
- HiLink features (Driverless, WEB UI, Auto connect)
- Plug and play
- Standard USB interface

2　Hardware

2.1　Hardware Specifications

Item	Specifications
Hardware Version	• CH1E3276SM
Technical standard	• LTE 3GPP R9 • HSPA+/UMTS: 3GPP R99/R5/R6/R7/R8 • GSM/GPRS/EDGE: 3GPP R99
External interfaces	USB: Type A with standard USB 2.0 High speed interface
	LED: indicating the status of the Data Card
	SD card: standard TF card interface
	SIM/USIM card: standard 6-pin SIM card interface
	RF interface: external RF interface
Maximum power consumption	$\leq$ 3.5 W
Power supply	5V
Dimensions (D × W × H)	About 92mm(D) × 32mm(W) × 14mm (H)
Weight	$\leq$ 50 g

Item	Specifications
Temperature	• Operating: –10℃ to +40℃ • Storage: –20℃ to +70℃
Humidity	5% to 95%
Base Information	• Plug and play (PnP)
	• Standard USB 2.0 High Speed interface, auto installation, convenient for use

Note:

3GPP = The 3rd Generation Partnership Project

TS = Technical Specification

LED = Light-Emitting Diode

SIM = Subscriber Identity Module

USIM = UMTS Subscriber Identity Module

3　Firmware

3.1　Version Description

Firmware Version:　　　22.470.13.00.00

Baseline information　　Balong V7R1 C35B270

3.2　Firmware Specifications

Firmware		
Item	**Specifications**	
Version	22.470.13.00.00	
Information	Platform	Balong V7R1
	Baseline	B270
	Feature	LTE Supported
Data service	GSM CS domain	• Uplink: 9.6/14.4 kbit/s • Downlink: 9.6/14.4 kbit/s
	GPRS	• Uplink: 85.6 kbit/s • Downlink: 85.6 kbit/s
	EDGE	• Uplink: 236.8 kbit/s • Downlink: 236.8 kbit/s
	UMTS PS domain	• Uplink: 384 kbit/s • Downlink: 384 kbit/s
	HSDPA	• 14.4Mbit/s
	HSUPA	• 5.76 Mbit/s

Firmware		
Item	**Specifications**	
	HSPA+	• 21.6Mbit/s
	DC HSPA+	• Uplink:5.76 Mbit/s • Downlink:43.2Mbit/s
	LTE FDD	• Uplink: 50Mbit/s • Downlink:130Mbit/s
SMS	• SMS over SGs	
Operating System	• Windows XP/Windows Vista/WIN 7/MAC/WIN8	

3.3 Improvement in the Previous Version

Index	Case ID	Issue Description

3.4 Known Limitations and Issues

Index	Case ID	Issue Description

4 WebUI/HiLink

4.1 Version Description

WebUI/HiLink Version: 17.100.03.01.03

4.2 WebUI/HiLink Specifications

Item	Specifications

4.3 Improvement in the Previous Version

Index	Case ID	Issue Description

4.4 Known Limitations and Issues

Index	Case ID	Issue Description
1		NA